

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

SAH  
#4A  
7-601

Pri rity Application Serial No. .... 09/449,025

Pri rity Filing Date ..... November 24, 1999

Inventor ..... Shozo Nagano et al.

Assignee ..... Honeywell International, Inc.

Priority Group Art Unit ..... 1775-1792

Examiner ..... Unknown

Attorney's Docket No. .... 30-5000-(4015)-Div1

Title: Conductive Integrated Circuit Metal Alloy Interconnections, Electroplating  
Anodes, Metal Alloys for Use as a Conductive Interconnection in an  
Integrated Circuit; and Physical Vapor Deposition Targets

PRELIMINARY AMENDMENT

To: Box Patent Application  
Assistant Commissioner for Patents  
Washington, D.C. 20231

From: Mark S. Matkin (Tel. 509-624-4276; Fax 509-838-3424)  
Wells, St. John, Roberts, Gregory & Matkin P.S.  
601 West First Avenue, Suite 1300  
Spokane, WA 99201-3817

Sir:

Please enter the following amendments prior to examining the above-identified  
application.

AMENDMENTS

In the Title

Please replace the title with the following: CONDUCTIVE INTEGRATED  
CIRCUIT METAL ALLOY INTERCONNECTIONS, ELECTROPLATING ANODES;  
METAL ALLOYS FOR USE AS A CONDUCTIVE INTERCONNECTION IN AN  
INTEGRATED CIRCUIT; AND PHYSICAL VAPOR DEPOSITION TARGETS.--